

ER-OLED027-3 Series

OLED Display Panel Datasheet



Eastrising Technology Co., Limited

Attention:

- A. Some specifications of IC are not listed in this datasheet. Please refer to the IC datasheet for more details.
- B. The related documents for interfacing, demo code, IC datasheet are all available, please download from our web.
- C. Please pay more attention to "INSPECTION CRITERIA" in this datasheet. We assume you already agree with these criterions when you place an order with us. No more recommendations.

REV	Description	Release Date
1.0	Preliminary Release	Aug-07-2025

CONTENTS

1. ORDER INFORMATION	04
1.1 Order Number	04
1.2 Image	04
2. SPECIFICATION	05
2.1 Display Specification	05
2.2 Mechanical Specification	05
2.3 Electrical Specification	05
2.4 Optical Specification	05
3. OUTLINE DRAWING	06
3.1 ER-OLED027-3 Outline Drawing	06
4. ELECTRICAL SPEC	07
4.1 Pin Configuration	07
4.2 Absolute Maximum Ratings	09
4.3 Electrical Characteristics	10
5. INSPECTION CRITERIA	11
5.1 Acceptable Quality Level	11
5.2 Definition of Lot	11
5.3 Condition of Cosmetic Inspection	11
5.4 Module Cosmetic Criteria	12
5.5 Screen Cosmetic Criteria (Non-Operating)	14
5.6 Screen Cosmetic Criteria (Operating)	15
6. PRECAUTIONS FOR USING	17
6.1 Handling Precautions	17
6.2 Power Supply Precautions	17
6.3 Operating Precautions	17
6.4 Mechanical/Environmental Precautions	18
6.5 Storage Precautions	18
6.6 Others	18

7. USING OLED MODULES	19
7.1 Liquid Crystal Display Modules	19
7.2 Installing OLED Modules	19
7.3 Precaution for Handling OLED Modules	19
7.4 Electro-Static Discharge Control	20
7.5 Precaution for Soldering to EastRising LCM	20
7.6 Precaution for Operation	20
7.7 Limited Warranty	21
7.8 Return Policy	21
8. IMAGE STICKING	22
8.1 What is Image Sticking?	22
8.2 What causes Image Sticking?	22
8.3 How to Avoid Image Sticking?	23
8.4 How to Fix the Image Sticking?	23
8.5 Is Image Sticking Covered by EastRising RMA Warranty?	23

1. ORDERING INFORMATION

1.1 Order Number

Order Number	Description
ER-OLED027-3W	White 2.7 inch OLED Display Panel with 16-Level Grayscale
ER-OLED027-3Y	Yellow 2.7 inch OLED Display Panel with 16-Level Grayscale

1.2 Image

ER-OLED027-3W ↓



ER-OLED027-3Y ↓



2. SPECIFICATION

2.1 Display Specification

Item	Standard Value	Unit
Display Format	256x128	Pixel
Display Connector	FPC-Connector	--
Operating Temperature	-40 ~ +70	°C
Storage Temperature	-40 ~ +85	°C
Sunlight Readable	No	--

2.2 Mechanical Specification

Item	Standard Value	Unit
Outline Dimension	73.00(W)x41.86(H)x2.0(T)	mm
Visual Area	63.41(W)x32.69(H)	mm
Active Area	61.42(W)x30.70(H)	mm
Dot Size	0.22x0.22	mm
Dot Pitch	0.24x0.24	mm

2.3 Electrical Specification

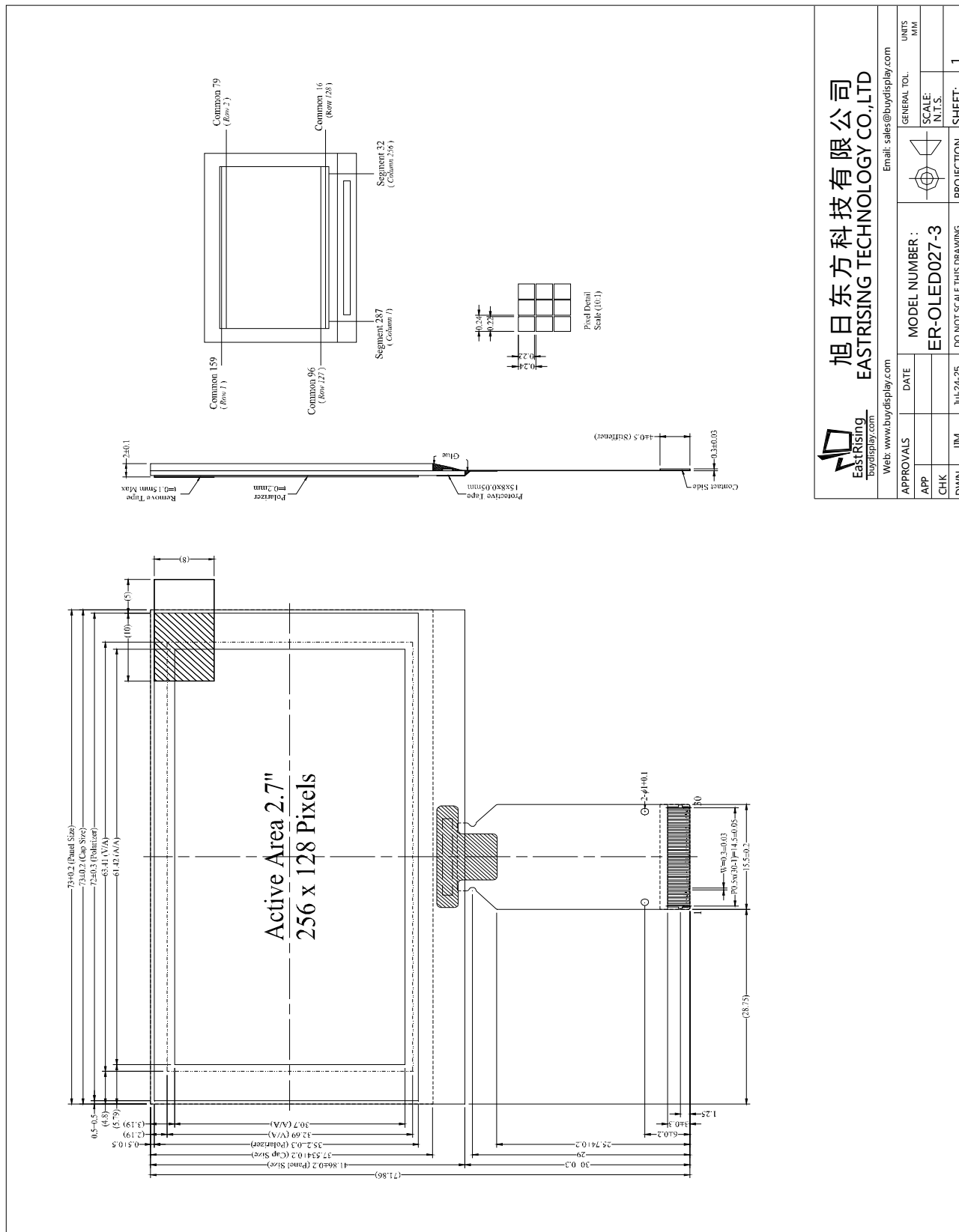
Item	Standard Value	Unit
IC Package	COG	--
Controller	SSD1363	--
Interface	8-bit 6800/8080 Parallel,4-Wire Serial SPI,I2C	--

2.4 Optical Specification

Item	Standard Value	Unit
Display Type	OLED (Passive Matrix) 16-Level Grayscale	--
Viewing Angle Range	Free	degree
OLED Duty	1/128	--

3. OUTLINE DRAWING

3.1 ER-OLED027-3 Outline Drawing



4. ELECTRICAL SPEC

4.1 Pin Configuration

Pin No	Pin Name	Description
1	GND	Reserved Pin (Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground as the ESD protection circuit.
2	VSS	Ground of Logic Circuit This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.
3	VCC	Power Supply for OEL Panel These are the most positive voltage supply pin of the chip. They must be connected to external source.
4	VCOMH	Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current at 10μA maximum. It should be kept floating when internal IREF is chosen by command setting.
5	VLSS	Ground of Analog Circuit These are the analog ground pins. They should be connected to VSS externally.
6~13	D7~D0	Host Data Input/Output Bus These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D2, D1 should be tied together as the serial data input: SDIN, and D0 will be the serial clock input: SCLK. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL.
14	E/RD#	Read/Write Enable or Read This pin is MCU interface input. When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 8080-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low. When serial or I2C interface is selected, this pin must be connected to VSS.
15	R/W#	Read/Write Select or Write This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode. When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled

		low. When serial or I2C interface is selected, this pin must be connected to VSS.															
16~17	BS2,BS1	Communicating Protocol Select These pins are MCU interface selection input. See the following table: <table> <tr> <th>Interface</th><th>BS1</th><th>BS2</th></tr> <tr> <td>4-wire Serial</td><td>0</td><td>0</td></tr> <tr> <td>I2C</td><td>1</td><td>0</td></tr> <tr> <td>8-bit 6800 Parallel</td><td>0</td><td>1</td></tr> <tr> <td>8-bit 8080 Parallel</td><td>1</td><td>1</td></tr> </table>	Interface	BS1	BS2	4-wire Serial	0	0	I2C	1	0	8-bit 6800 Parallel	0	1	8-bit 8080 Parallel	1	1
Interface	BS1	BS2															
4-wire Serial	0	0															
I2C	1	0															
8-bit 6800 Parallel	0	1															
8-bit 8080 Parallel	1	1															
18	D/C#	Data/Command Control This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register. When the pin is pulled high and serial interface mode is selected, the data at SDIN is treated as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection.															
19	CS#	Chip Select This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.															
20	RES#	Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed. Keep this pin pull high during normal operation.															
21	FR	Frame Frequency Triggering Signal This pin outputs RAM write synchronization signal. Proper timing between MCU data writing and frame display timing can be achieved to prevent tearing effect. It should be kept NC if it is not used.															
22	IREF	Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current at 10μA maximum. It should be kept floating when internal IREF is chosen by command setting.															
23	NC	Reserved Pin The N.C. pin between function pins is reserved for compatible and flexible design															
24	VDD	Power Supply for Core Logic Circuit Power supply pin for core logic operation. A capacitor should be connected between this pin and VSS.															
25	VP	Power Supply for segment pre-charge voltage reference This pin is the segment pre-charge voltage reference pin. A capacitor can be connected between this pin and VSS to improve visual performance. It can also be float per application.															

		No external power supply is allowed to connect to this pin.
26	NC	Reserved Pin The N.C. pin between function pins is reserved for compatible and flexible design
27	VSL	Voltage Output Low Level for SEG Signal This is segment voltage reference pin. This pin has to be connected with resistor and diode to ground (details depends on application).
28	VLSS	Ground of Analog Circuit These are the analog ground pins. They should be connected to VSS externally.
29	VCC	Power Supply for OEL Panel These are the most positive voltage supply pin of the chip. They must be connected to external source.
30	GND	Reserved Pin (Supporting Pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground as the ESD protection circuit.

4.2 Absolute Maximum Ratings

Parameter	Symbol	MIN	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1,2
Supply Voltage for Display	VCC	-0.3	19	V	1,2
Life Time(60cd/m ²)	-	15000	-	Hour	4

Note 1: All the above voltages are on the basis of "VSS = 0V" .

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Optics & Electrical Characteristics" . If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate. The defined temperature ranges do not include the polarizer.

The maximum withstood temperature of the polarizer should be 80℃.

Note 4: VCC = 15V, Ta = 25°C, 50% Checkerboard.

End of lifetime is specified as 50% of initial brightness reached. The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

4.3 Electrical Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Supply Voltage for Operation	VDD		2.6	3.0	3.5	V
Supply Voltage for Display	VCC	Note 5	14.5	15	15.5	V
High Level Output	VIH		0.8xVDD	-	VDD	V
Low Level Output	VIL		0	-	0.2xVDD	V
High Level Output	VOH	IOUT = 100μA	0.9xVDD	-	VDD	V
Low Level Output	VOL	IOUT = 100μA	0		0.1xVDD	
Operating Current for VDD	IDD		-	0.8	1	mA
Operating Current for VCC (VCC Supplied Externally)	ICC	Note 6	-	--	75	mA
Sleep Mode Current for VDD	IDD,SLEEP		-	-	10	μA
Sleep Mode Current for VPP	IPP,SLEEP		-	-	10	μA

Note 5: Brightness (Lbr) and Supply Voltage for Display (VCC) are subject to the change of the panel characteristics and the customer' s request.

Note 6: VDD = 2.8V, VCC = 15.0V, 100% Display Area Turn on.

5. INSPECTION CRITERIA

5.1 Acceptable Quality Level

Each lot should satisfy the quality level defined as follows

Partition	AQL	Definition
A. Major	0.4%	Functional defective as product
B. Minor	1.5%	Satisfy all functions as product but not satisfy cosmetic standard

5.2 Definition of Lot

One lot means the delivery quantity to customer at one time.

5.3 Condition of Cosmetic Inspection

◆ INSPECTION AND TEST

-FUNCTION TEST

-APPEARANCE INSPECTION

-PACKING SPECIFICATION

◆ INSPECTION CONDITION

- Put under the lamp (20W) at a distance 100mm from

- Tilt upright 45 degree by the front (back) to inspect OLED appearance.

◆ AQL INSPECTION LEVEL

- SAMPLING METHOD: MIL-STD-105D

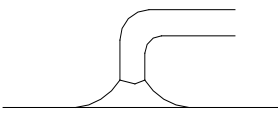
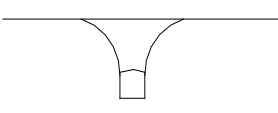
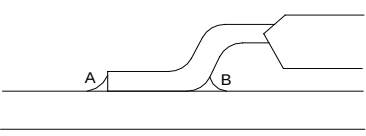
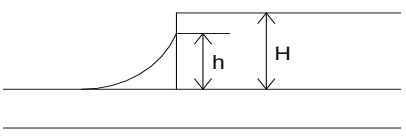
- SAMPLING PLAN: SINGLE

- MAJOR DEFECT: 0.4% (MAJOR)

- MINOR DEFECT: 1.5% (MINOR)

- GENERAL LEVEL: II/NORMAL

5.4 Module Cosmetic Criteria

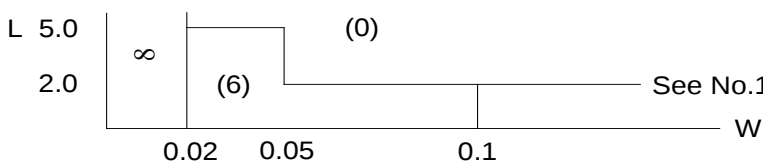
No.	Item	Judgment Criterion	Partition
1	Difference in Spec.	None allowed	Major
2	Pattern Peeling	No substrate pattern peeling and floating	Major
3	Soldering Defects	No soldering missing	Major
		No soldering bridge	Major
		No cold soldering	Minor
4	Resist Flaw on Substrate	Invisible copper foil(ϕ 0.5mm or more)on substrate pattern	Minor
5	Accretion of Metallic Foreign Matter	No soldering dust	Minor
		No accretion of metallic foreign matters(Not exceed ϕ 0.2mm)	
6	Stain	No stain to spoil cosmetic badly	Minor
7	Plate Discoloring	No plate fading, rusting and discoloring	Minor
8	Solder Amount 1.Lead Parts	a. Soldering side of PCB Solder to form a 'Filet' all around t Solder should not hide the lead form  b.Components side (In case of 'Through Hole PCB') Solder to reach the Components side of PCB 	Minor
	2.Flat Packages	Either 'toe' (A) or 'heel' (B) of the lead to be covered by Filet'  Lead form to be assume over solder.	Minor
	3.Chips	$(3/2) H \geq h \geq (1/2)H$ 	Minor

9	Backlight Defects	1.Light fails or flickers.(Major) 2. Color and luminance do not correspond to specifications. (Major) 3.Exceeds standards for display' s blemishes, foreign matter, dark lines or scratches.(Minor)	See list ←
10	PCB Defects	Oxidation or contamination on connectors.* 2. Wrong parts, missing parts, or parts not in specification.* 3.Jumpers set incorrectly.(Minor) 4.Solder(if any)on bezel, LED pad, zebra pad, or screw hole pad is not smooth.(Minor) *Minor if display functions correctly. Major if the display fails.	See list ←
11	Soldering Defects	1. Unmelted solder paste. 2. Cold solder joints, missing solder connections, or oxidation.* 3. Solder bridges causing short circuits.* 4. Residue or solder balls. 5. Solder flux is black or brown. *Minor if display functions correctly. Major if the display fails.	Minor

5.5 Screen Cosmetic Criteria (Non-Operating)

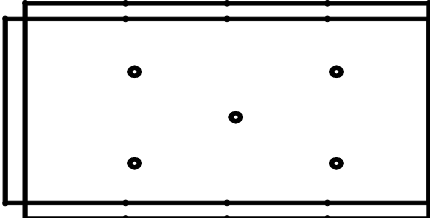
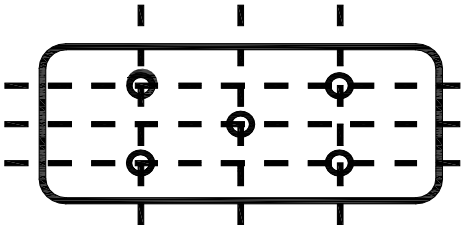
No.	Defect	Judgment Criterion	Partition
1	Spots	In accordance with Screen Cosmetic Criteria (Operating) No.1.	Minor
2	Lines	In accordance with Screen Cosmetic Criteria (Operation) No.2.	Minor
3	Bubbles in Polarizer		Minor
		Size: d mm	
		Acceptable Qty in active area	
		d≤0.3	
		Disregard	
		0.3<d≤1.0	3
		1.0<d≤1.5	1
		1.5<d	0
4	Scratch	In accordance with spots and lines operating cosmetic criteria, When the light reflects on the panel surface, the scratches are not to be remarkable.	Minor
5	Allowable density	Above defects should be separated more than 30mm each other.	Minor
6	Coloration	Not to be noticeable coloration in the viewing area of the OLED panels. Back-lit type should be judged with back-lit on state only.	Minor
7	Contamination	Not to be noticeable.	Minor

5.6 Screen Cosmetic Criteria (Operating)

No.	Defect	Judgment Criterion	Partition	
1	Spots	A) Clear	Minor	
		Size:d mm		Acceptable Qty in active area
		d≤0.1		Disregard
		0.1 < d ≤ 0.2		6
		0.2 < d ≤ 0.3		2
		0.3 < d		0
Note: Including pin holes and defective dots which must be within one pixel Size. Unclear				
Size:d mm	Acceptable Qty in active area			
d≤0.2	Disregard			
0.2 < d ≤ 0.5	6			
0.5 < d ≤ 0.7	2			
0.7 < d	0			
2	Lines	A) Clear	Minor	
				
		Note: () – Acceptable Qty in active area L - Length (mm) W -Width(mm) ∞-Disregard		
B) Unclear				

Clear’ = The shade and size are not changed by Vo.

Unclear’ = The shade and size are changed by Vo.

No.	Defect	Judgment Criterion	Partition
3	Rubbing line	Not to be noticeable.	Minor
4	Allowable density	Above defects should be separated more than 10mm each other.	Minor
5	Rainbow	Not to be noticeable.	Minor
6	Dot size	To be 95%~105%of the dot size (Typ.) in drawing. Partial defects of each dot (ex.pin-hole) should be treated as spot. (see Screen Cosmetic Criteria (Operating) No.1)	Minor
7	Brightness (only back-lit Module)	Brightness Uniformity must be $B_{MAX}/B_{MIN} \leq 2$ - BMAX : Max.value by measure in 5 points - BMIN : Min.value by measure in 5 points Divide active area into 4 vertically and horizontally. Measure 5 points shown in the following figure. 	Minor
8	Contrast Uniformity	Contrast Uniformity must be $B_{mAX}/B_{mIN} \leq 2$ Measure 5 points shown in the following figure. Dashed lines divide active area into 4 vertically and horizontally. Measuring points are located at the inter-sections of dashed line.  Note: BMAX – Max.value by measure in 5 points. BMIN – Min.value by measure in 5 points. O – Measuring points in $\phi 10mm$.	Minor

Note:

(1) Size: $d = (\text{long length} + \text{short length}) / 2$

(2) The limit samples for each item have priority.

(3) Complexed defects are defined item by item, but if the number of defects is defined in above table, the total number should not exceed 10.

(4) In case of 'concentration', even the spots or the lines of 'disregarded' size should not be allowed. Following three situations should be treated as 'concentration'.

-7 or over defects in circle of $\phi 5mm$.

-10 or over defects in circle of $\phi 10mm$

-20 or over defects in circle of $\phi 20mm$

6. PRECAUTIONS FOR USING

6.1 Handling Precautions

- ◆ This device is susceptible to Electro-Static Discharge (ESD) damage. Observe Anti-Static precautions.
- ◆ EastRising display panel is made of glass. Do not subject it to a mechanical shock by dropping it or impact.
- ◆ If EastRising display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- ◆ Do not apply excessive force to the EastRising display surface or the adjoining areas since this may cause the color tone to vary.
- ◆ The polarizer covering the EastRising display surface of the OLED module is soft and easily scratched. Handle this polarizer carefully.
- ◆ If EastRising display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following Isopropyl or alcohol.
- ◆ Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the Water.
- ◆ Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
- ◆ Install the EastRising OLED Module by using the mounting holes. When mounting the OLED module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the cable or the backlight cable.
- ◆ Do not attempt to disassemble or process EastRising OLED module.
- ◆ NC terminal should be open. Do not connect anything.
- ◆ If the logic circuit power is off, do not apply the input signals.
- ◆ To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling EastRising OLED modules.
 - Tools required for assembling, such as soldering irons, must be properly grounded.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions.
- The OLED module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

6.2 Power Supply Precautions

- ◆ Identify and, at all times, observe absolute maximum ratings for both logic and LC drivers. Note that there is some variance between models.
- ◆ Prevent the application of reverse polarity to VDD and VSS, however briefly.
- ◆ Use a clean power source free from transients. Power-up conditions are occasionally jolting and may exceed the maximum ratings of EastRising modules.
- ◆ The VDD power of EastRising module should also supply the power to all devices that may access the display. Don't allow the data bus to be driven when the logic supply to the module is turned off.

6.3 Operating Precautions

- ◆ DO NOT plug or unplug EastRising module when the system is powered up.
- ◆ Minimize the cable length between EastRising module and host MPU.
- ◆ For models with backlights, do not disable the backlight by interrupting the HV line. Unload inverters produce voltage extremes that may arc within a cable or at the display.

- ♦ Operate EastRising module within the limits of the modules temperature specifications.

6.4 Mechanical/Environmental Precautions

- ♦ Improper soldering is the major cause of module difficulty. Use of flux cleaner is not recommended as they may seep under the electrometric connection and cause display failure.
- ♦ Mount EastRising module so that it is free from torque and mechanical stress.
- ♦ Surface of the OLED panel should not be touched or scratched. The display front surface is an easily scratched, plastic polarizer. Avoid contact and clean only when necessary with soft, absorbent cotton dampened with petroleum benzene.
- ♦ Always employ anti-static procedure while handling EastRising module.
- ♦ Prevent moisture build-up upon the module and observe the environmental constraints for storage tem
- ♦ Do not store in direct sunlight
- ♦ If leakage of the liquid crystal material should occur, avoid contact with this material, particularly ingestion. If the body or clothing becomes contaminated by the liquid crystal material, wash thoroughly with water and soap.

6.5 Storage Precautions

When storing the OLED modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

Keep EastRising modules in bags (avoid high temperature / high humidity and low temperatures below 0 °C).

Whenever possible, EastRising OLED modules should be stored in the same conditions in which they were shipped from our company.

6.6 Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature. If EastRising OLED modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the OLED modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

- Exposed area of the printed circuit board.
- Terminal electrode sections.

7. USING OLED MODULES

7.1 Liquid Crystal Display Modules

EastRising OLED is composed of glass and polarizer. Pay attention to the following items when handling.

- ◆ Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.
- ◆ Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.).
- ◆ N-hexane is recommended for cleaning the adhesives used to attach front/rear polarizers and reflectors made of organic substances which will be damaged by chemicals such as acetone, toluene, ethanol and isopropyl alcohol.
- ◆ When EastRising display surface becomes dusty, wipe gently with absorbent cotton or other soft material like chamois soaked in petroleum benzin. Do not scrub hard to avoid damaging the display surface.
- ◆ Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading.
- ◆ Avoid contacting oil and fats.
- ◆ Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizers. After products are tested at low temperature they must be warmed up in a container before coming in contact with room temperature air.
- ◆ Do not put or attach anything on EastRising display area to avoid leaving marks on.
- ◆ Do not touch the display with bare hands. This will stain the display area and degrade insulation between terminals (some cosmetics are determined to the polarizers).
- ◆ As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping.

7.2 Installing OLED Modules

- ◆ Cover the surface with a transparent protective plate to protect the polarizer and LC cell.
- ◆ When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be $\pm 0.1\text{mm}$.

7.3 Precaution for Handling OLED Modules

Since EastRising LCM has been assembled and adjusted with a high degree of precision; avoid applying excessive shocks to the module or making any alterations or modifications to it.

- ◆ Do not alter, modify or change the shape of the tab on the metal frame.
- ◆ Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- ◆ Do not damage or modify the pattern writing on the printed circuit board.
- ◆ Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- ◆ Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- ◆ Do not drop, bend or twist EastRising LCM.

7.4 Electro-Static Discharge Control

Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC.

- ◆ Make certain that you are grounded when handling LCM.
- ◆ Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential.
- ◆ When soldering the terminal of LCM, make certain the AC power source for the soldering iron does not leak.
- ◆ When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- ◆ As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.
- ◆ To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended.

7.5 Precaution for Soldering to EastRising LCM

- ◆ Observe the following when soldering lead wire, connector cable and etc. to the LCM.
 - Soldering iron temperature : $280^{\circ}\text{C} \pm 10^{\circ}\text{C}$
 - Soldering time: 3-4 sec.
 - Solder: eutectic solder.

If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the OLED surface with a cover during soldering to prevent any damage due to flux spatters.

- ◆ When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- ◆ When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PCs board could be damaged.

7.6 Precaution for Operation

- ◆ Driving the EastRising OLED in the voltage above the limit shortens its life.
- ◆ Response time is greatly delayed at temperature below the operating temperature range. However, this does not mean the OLED will be out of the order. It will recover when it returns to the specified temperature range.
- ◆ If EastRising display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.
- ◆ Condensation on terminals can cause an electrochemical reaction disrupting the terminal circuit. Therefore, it must be used under the relative condition of 40°C , 50% RH.
- ◆ When turning the power on, input each signal after the positive/negative voltage becomes stable.

7.7 Limited Warranty

Unless agreed between EastRising and customer, EastRising will replace or repair any of its OLED modules which are found to be functionally defective when inspected in accordance with EastRising OLED acceptance standards (copies available upon request) for a period of one year from date of shipments. Cosmetic/visual defects must be returned to EastRising within 90 days of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EastRising limited to repair and/or replacement on the terms set forth above. EastRising will not be responsible for any subsequent or consequential events.

7.8 Return Policy

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are:

- Broken OLED glass.
- PCB eyelet damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet's, conductors and terminals.

8. IMAGE STICKING

8.1 What is Image Sticking?

If you remain a fixed image on OLED Display for a long period of time, you may experience a phenomenon called Image Sticking. Image Sticking - sometimes also called "image retention" or "ghosting" - is a phenomenon where a faint outline of a previously displayed image remains visible on the screen when the image is changed. It can occur at variable levels of intensity depending on the specific image makeup, as well as the amount of time the core image elements are allowed to remain unchanged on the screen. In POS applications, for example, a button menu which remains fixed, or in which the "frame" elements (core image) remain fixed and the buttons may change, may be susceptible to image sticking. It is important to note that if the screen is used exclusively for this application, the user may never notice this phenomenon since the screen never displays other content. It is only when an image other than the "retained" image is shown on the screen that this issue becomes evident. Image sticking is different than the "burn-in" effect commonly associated with phosphor based devices.

8.2 What causes Image Sticking?

Image sticking is an intrinsic behavior of OLED displays due to the susceptibility to polarization of the interior materials (liquid crystals) when used under static, charged conditions (continuously displaying the same image). The individual liquid crystals in an OLED panel have unique electrical properties. Displaying a fixed pattern - such as the POS menu described above - over prolonged periods can cause a parasitic charge build-up (polarization) within the liquid crystals which affects the crystals' optical properties and ultimately prevents the liquid crystal from returning to its normal, relaxed state when the pattern is finally changed. This effect takes place at a cellular level within the OLED, and the effect can cause charged crystal alignment at the bottom or top of a crystal cell in the "z" axis, or even crystal migration to the edges of a cell, again based on their polarity. These conditions can cause image sticking over an entire area, or at boundaries of distinct color change respectively. In either case, when the liquid crystals in the pixels and sub-pixels utilized to display the static image are polarized such that they can not return fully to their "relaxed" state upon deactivation, the result is a faint, visible, retained image on the panel upon presentation of a new, different image. The actual rate of image retention depends on variation factors such as the specific image, how long it is displayed unchanged, the temperature within the panel and even the specific panel brand due to manufacturing differences amongst panel manufacturers.

8.3 How to Avoid Image Sticking?

- Try not to operate the OLED with a "fixed" image on the screen for more than 2 hours.
- If you are operating the monitor in an elevated temperature environment and with a displayed image which is contrary to the recommendations in "For Software Developers" below, image stick can occur in as little as 30 minutes. Adjust your screen saver settings accordingly.
- Power down the unit during prolonged periods of inactivity such as the hours a store is closed or a shift during which the piece of equipment isn't used.
- Use a screensaver with a black or medium gray background that is automatically set to come on if the device is inactive for more than 5-10 minutes.
- Avoid placing the monitor in poorly ventilated areas or in areas that will create excess heat around the monitor for software developers.
- In defining the icons, buttons, or windows in the screen, try to utilize block patterns instead of distinct lines as borders for dividing the display into distinct areas.
- If it is necessary to display a static image, try to use colors that are symmetric to the middle grey level at the boundary of two different colors, and slightly shift the borders line once in a while.
- Try to utilize medium gray hues for those areas that will have prolonged display times or remain static as other menu elements change.

8.4 How to Fix the Image Sticking?

Unlike the usually irreversible "burn-in" effects commonly associated with direct view phosphor display devices such as CRTs, an image retained on an OLED display can be reversed – often to a point of total invisibility. However, the severity of the underlying causes (as described above) of the image retained on a specific display, as well as the variation factors (see "For Software Developers" above) under which the retained image was created, will dictate the final level of retention reversal. One way to erase a retained image on a panel is to run the screen (monitor "on") in an "all black" pattern for 4-6 hours. It is also helpful to do this in an elevated temperature environment of approximately 35° to 50°C. Again, utilizing a dynamic screen saver with an all black background during prolonged idle display periods is a good way to avoid image retention issues.

8.5 Is Image Sticking Covered by EastRising RMA Warranty?

Image sticking is a phenomenon inherent to OLED Display technology itself, and as such, the occurrence of this "ghosting" effect is considered normal operation by the manufacturers of the OLED display modules which are integrated into today's monitor solutions. EastRising does not warrant any display against the occurrence of image sticking. We strongly advise that you follow the operating recommendations listed above to avoid the occurrence of this phenomenon.

That's the end of the datasheet.